

●LGA-4B01 Power Dissipation

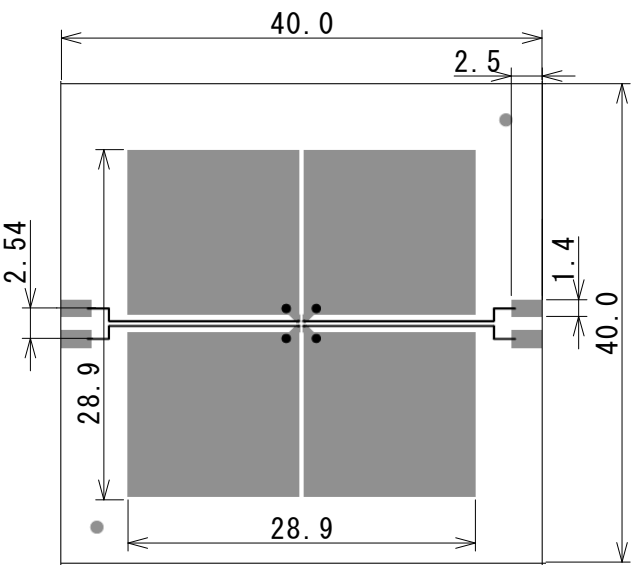
Power dissipation data for the LGA-4B01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board : Dimensions 40 x 40 mm (1600 mm² in one side)
- Copper (Cu) traces occupy 50% of the front and 50% of the back.
- The copper area is divided into four block,
- one block is 12.5% of total.
- Each terminal connects one copper block in the front and one in the back.
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6mm
- Through-hole : 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	600	166.67
85	240	

